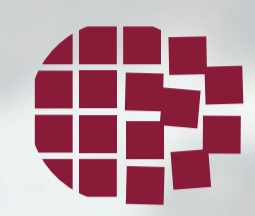


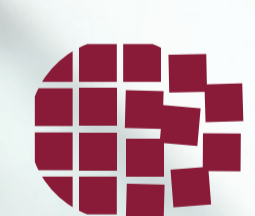


MULTIBEAM LASER DICING SYSTEM



The ALSI laser separation system is designed for ALSI's multibeam laserdicing technology:

- High dicing speed: >500 mm/sec
- High accuracy: $<0,5 \mu\text{m}$
- High acceleration: $>1\text{G}$



and is based on state of the art and proven mechatronics and control technologies and includes:

- Active focus control to compensate any wafer thickness variations
- Planar motion and active mounts for vibration compensations
- Remote control and diagnostics
- Cassette to cassette wafer handling